

Title (en)

METHOD FOR PRODUCING ELECTRICALLY CONDUCTIVE SURFACES ON A CARRIER

Title (de)

VERFAHREN ZUR HERSTELLUNG VON ELEKTRISCH LEITFÄHIGEN OBERFLÄCHEN AUF EINEM TRÄGER

Title (fr)

PROCÉDÉ DE FABRICATION DE SURFACES ÉLECTRIQUEMENT CONDUCTRICES SUR UN SUPPORT

Publication

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Application

EP 07765353 A 20070611

Priority

- EP 2007055701 W 20070611
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Abstract (en)

[origin: WO2007144322A1] Method for producing electrically conductive, structured or whole-area surfaces on a carrier, in which a first step involves applying a structured or whole-area base layer to the carrier with a dispersion containing electrically conductive particles in a matrix material, a second step involves at least partly curing or drying the matrix material, a third step involves uncovering the electrically conductive particles by at least partly breaking up the matrix, and a fourth step involves forming a metal layer on the structured or whole-area base layer by means of electroless or electrolytic coating.

IPC 8 full level

H05K 3/10 (2006.01); **H05K 3/24** (2006.01)

CPC (source: EP KR US)

H05K 1/00 (2013.01 - KR); **H05K 3/18** (2013.01 - KR); **H05K 3/24** (2013.01 - KR); **H05K 3/246** (2013.01 - EP US); **H05K 1/095** (2013.01 - EP US); **H05K 2201/0347** (2013.01 - EP US); **H05K 2203/025** (2013.01 - EP US); **H05K 2203/0257** (2013.01 - EP US); **H05K 2203/0789** (2013.01 - EP US); **H05K 2203/0796** (2013.01 - EP US); **H05K 2203/095** (2013.01 - EP US); **H05K 2203/097** (2013.01 - EP US); **H05K 2203/107** (2013.01 - EP US)

Citation (search report)

See references of WO 2007144322A1

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DOCDB simple family (publication)

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